

	SPECIFICATION	S
CUSTOMER	· PTC	
SAMPLE CODE	: SH48027	2T-006-I01Q
MASS PRODUCTION CODE	PH48027	2T-006-I01Q
SAMPLE VERSION	. 03	
SPECIFICATIONS EDITION	. 010	
DRAWING NO. (Ver.)	JLMD-PH	1480272T-006-I01Q_004
PACKAGING NO. (Ver.)	JPKG-PH	1480272T-006-I01Q_001
		Date: 2016.02.23
Approved	Checked	Date: 2016.02.23
Approved	Checked 張久慧	Date: 2016.02.23
□ Preliminary specification ■ Specification for sample	張久慧 for design input	Date: IND APPROVED IND APPROV



History of Version

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
06/02/2010	01	001	New Drawing.	-	Violin Huang
7/22/2010	01	002	New Sample	-	Violin Huang
1/24/2013	02	003	Modify VR height & size	-	趙冬冬
2/07/2013	02	004	Reliability Test Condition and add MTBF	4 • 24	Rex
4/30/2013	02	005	Add flicker free and Life Time. Bright /Dark And Broken Dot Measure Up ISO 9241-307 and modify the tolerance	6 • 9 • 18 • Appendix	趙冬冬
04/09/2014	02	006	Update Specification	-	劉進
06/09/2014	03	007	Change Backlight	6 • 9	劉進
08/18/2015	03	008	Show Backlight Life Time	9	劉進
02/19/2016	03	009	Change Backlight Characteristics	9	劉進
02/23/2016	03	010	Update Average Brightness	6	劉進
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Total: 26 Page



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1. SPECIFICATIONS

1.1 Features

Item	Standard Value			
Display Type	480 * 3 (RGB) * 272 Dots			
LCD Type	a-Si TFT, Normally white, Transmissive type			
Screen size(inch)	4.3 inch			
Viewing Direction	6 O'clock			
Color configuration	RGB-Strip			
Interface	Digital 24-bits RGB			
Other/controller/driver IC)	OTA5180A			
Other(controller/driver IC)	(Or Compatible IC)			
	THIS PRODUCT CONFORMS THE ROHS OF PTC			
ROHS	Detail information please refer web site :			
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/			

1.2 Mechanical Specifications

Item	Standard Value	
Outline Dimension	105.5(W) x 67.2 (L) x 3.5(H)	mm
Viewing Area	96.64(W) x 55.456 (L)	
Active Area	95.04 (W) * 53.856 (L)	mm

Note : For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
System Power Supply Voltage	VDDIO	GND=0	-0.3	4.5	V
Operating Temperature	Тор	-	-20	70	°C
Storage Temperature	Tst	-	-30	80	°C



1.4 DC Electrical Characteristics

Module		$GND = 0V, Ta = 25^{\circ}C$				
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VDDIO	-	3.0	3.3	3.6	V
	VIH	-	0.7VDDIO	-	VDDIO	V
Input H/L Level Voltage	VIL	-	0	-	0.3VDDIO	V
Output H/L Level	VOH	-	VDDIO-0.4	·	VDDIO	V
Voltage	VOL	-	0	-	GND+0.4	V
Supply Current	IDD	VDDIO = 3.3 V	-	12.5	20.0	mA



1.5 Optical Characteristics

TFT LCD Module

VDDIO= 3.3 V, Ta=25°C

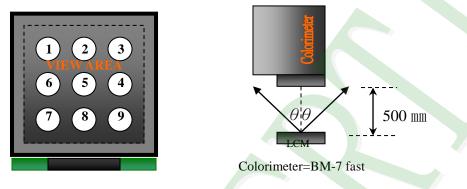
				,				
ltem		Symbol	Condition	Min.	Тур.	Max.	unit	-
Response time	Tr+Tf	25°C	-	-	30	45	ms	-
	Тор	θY+		-	60	-		
	Bottom	θY-	CR ≥ 10	-	60	-	Deg	Nota 1
Viewing angle	Left	θХ-	CR 2 10	-	60	-	Deg.	Note 4
	Right	θX+		-	60	-		
Contrast rati	0	CR	-	500	600	-	1	Note 3
	White	Х		0.25	0.30	0.35		
	vvnite	Y		0.29	0.34	0.39		
	Red	Х		0.54	0.59	0.64		
Color of CIE Coordinate	Reu	Y	IF= 20 mA	0.30	0.35	0.40		Note1
(With B/L)	Orean	Х	IF = 20 IIIA	0.29	0.34	0.39	-	noter
	Green	Y		0.56	0.61	0.66		
	Blue	Х		0.10	0.15	0.20		
	Diue	Y		0.07	0.12	0.17		
Average Brightr	ness							
Pattern=white di	splay	IV	IF= 20 mA	260	390	-	cd/m²	Note1
(With B/L)*1								
		∆B	IF= 20 mA	70	-	-	%	Note1
(With B/L)*2	<u> </u>							

Note: Vcom adjustment assures flicker free with customer test picture.



Note 1:

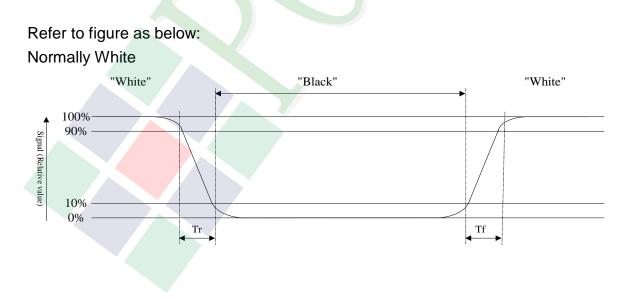
- *1 : △B=B(min) / B(max) * 100%
- *2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25°C±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: 500 \pm 50 mm \rightarrow (θ = 0°)
 - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%



To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

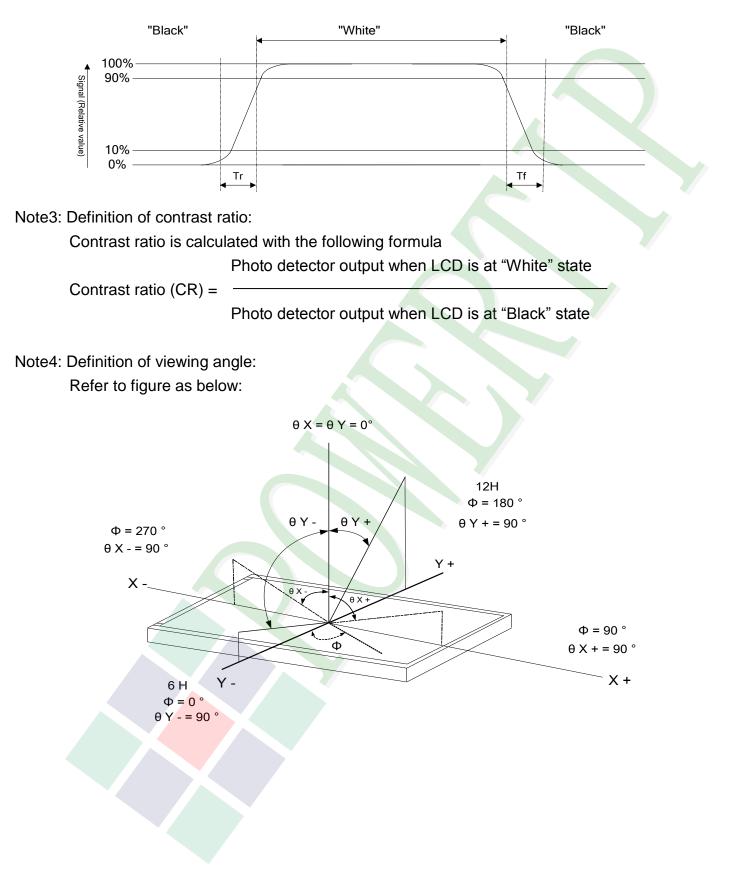
Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.





Normally Black





1.6 Backlight Characteristics

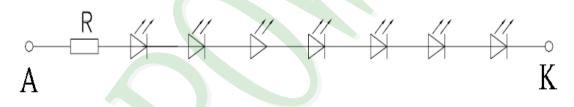
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
LED Forward Current	IF	Ta =25℃	-	30	mA
LED Reverse Voltage	VR	Ta =25℃	-	7	V
Power Dissipation	PD	Ta =25℃	-	490	mW

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF		19.6	22.8	24.5	V
Average Brightness (Without LCD)	IV	IF= 20 mA	5000	6000	-	cd/m ²
CIE Color Coordinate	Х		0.26	0.30	0.34	
(Without LCD)	Y		0.26	0.30	0.34	-
Color			White			

Circuit diagram:



Other Description

Item	Conditions	Description
Life Time	Ta =25℃ IF= 20mA	20000 hrs



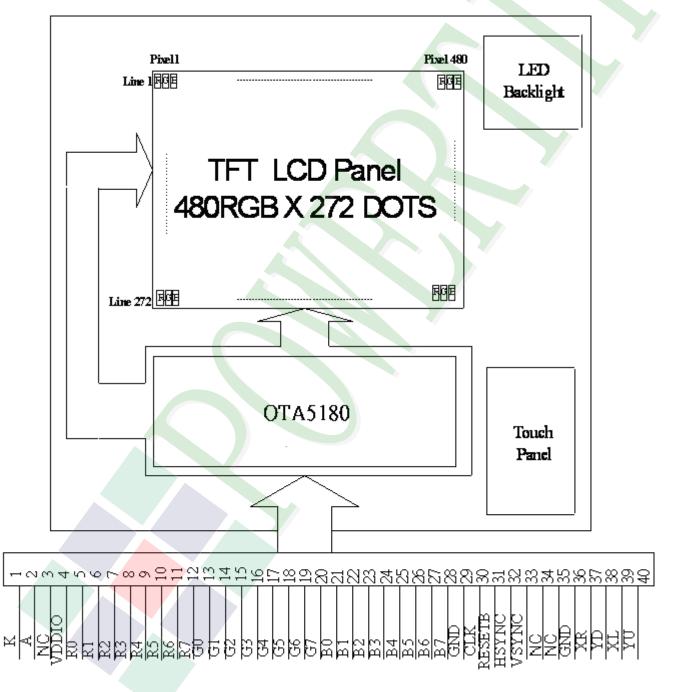
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram



POWERTIP

2.2 Interface Pin Description

Pin No.	Symbol	Function
1	K	Power supply for LED Backlight cathode input
2	А	Power supply for LED Backlight anode input
3	NC	No connection
4	VDDIO	Digital power
5	R0	Red data bit 0
6	R1	Red data bit 1
7	R2	Red data bit 2
8	R3	Red data bit 3
9	R4	Red data bit 4
10	R5	Red data bit 5
11	R6	Red data bit 6
12	R7	Red data bit 7
13	G0	Green data bit 0
14	G1	Green data bit 1
15	G2	Green data bit 2
16	G3	Green data bit 3
17	G4	Green data bit 4
18	G5	Green data bit 5
19	G6	Green data bit 6
20	G7	Green data bit 7



Pin No.	Symbol	Function
21	B0	Blue data bit 0
22	B1	Blue data bit 1
23	B2	Blue data bit 2
24	B3	Blue data bit 3
25	B4	Blue data bit 4
26	B5	Blue data bit 5
27	B6	Blue data bit 6
28	B7	Blue data bit 7
29	GND	Ground
30	CLK	Dot data clock
31	RESETB	Active low global reset signal input.
32	HSYNC	Horizontal sync input
33	VSYNC	Vertical sync input
34	NC	No connection
35	NC	No connection
36	GND	Ground
37	XR	NC
38	YD	NC
39	XL	NC
40	YU	NC



2.3 Timing Characteristics

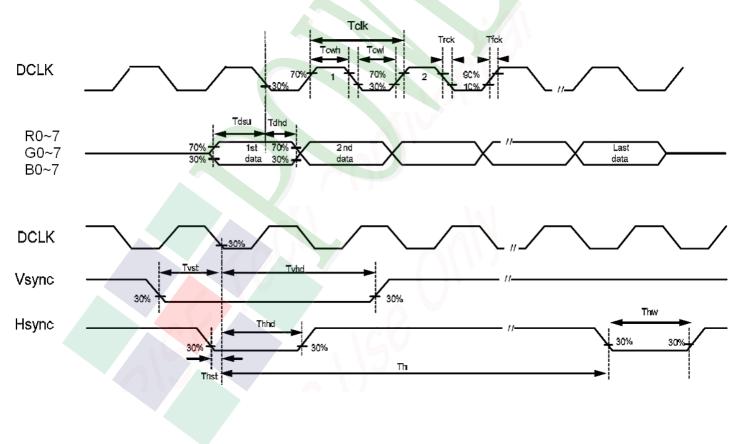
2.3.1 AC Characteristics

VDDIO=3.3V, TA=-20~70°C

Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
CLK pulse duty	Tcw	40	50	60	%	
Hsync width	Thw	1.0		-	DCLK	
Hsync period	Th	55	60	65	us	
∨sync setup time	Tvst	12	<u>у</u> -	-	ns	
∨sync hold time	Tvhd	12	-	-	ns	
Hsync setup time	Thst	12	-	-	ns	
Hsync hold time	Thhd	12	-	-	ns	
Data set-up time	Tdsu	12	-		ns	
Data hold time	Tdhd	12	-	-	ns	
SD output stable time	Tst	-	10	12	us	
GD output rise and fall time	Tgst	-	500	1000	ns	

2.3.2 AC Timing Diagram

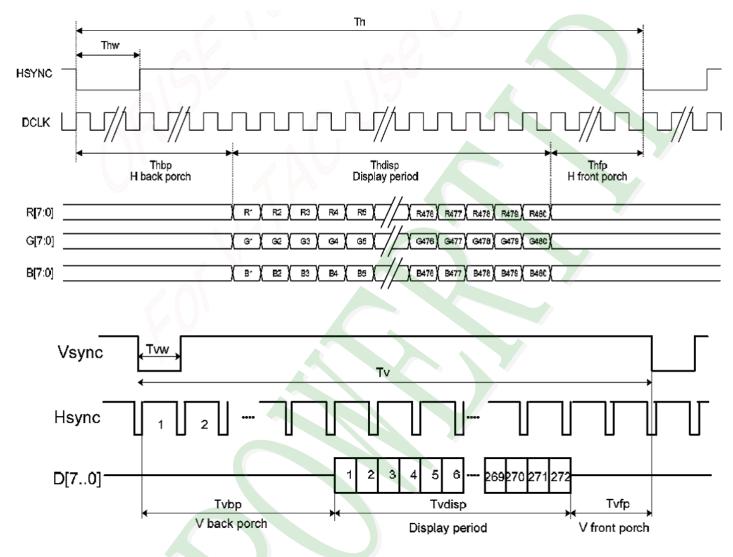
Clock and Data Input Timing Diagram





2.4 Data Format

2.4.1 Parallel RGB Input Timing Diagram



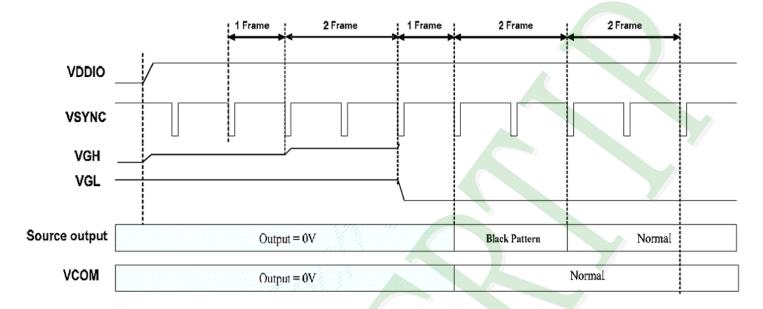
2.4.2 Parallel RGB Input Timing Table

	Item		Min.	Тур.	Max.	Unit	
CLK F	CLK Frequency		5	9	12	MHz	
CLK F	Period	Tclk	83	110	200	ns	
Hsync	Period Time	Th	490	531	605	DCLK	
	Display Period	Thdisp		480 (5)		DCLK	
	Back Porch	Thbp	8	43		DCLK	By H_BLANKING setting
	Front Porch	Thfp	2	8	<u>ک</u>	DCLK	
	Pulse Width	Thw	1 (D (()) / /		DCLK	
Vsync	Period Time	Tv	275	288	335	н	
	Display Period	Tvdisp		272		Н	
	Back Porch	Tvbp	2	12	<u> </u>	Н	By V_BLANKING setting
	Front Porch	Tvfp	$\mathbb{C}^{\mathbb{N}}$	4		Н	
	Pulse Width	Txŵ (6)	NU/A	10		N) H	

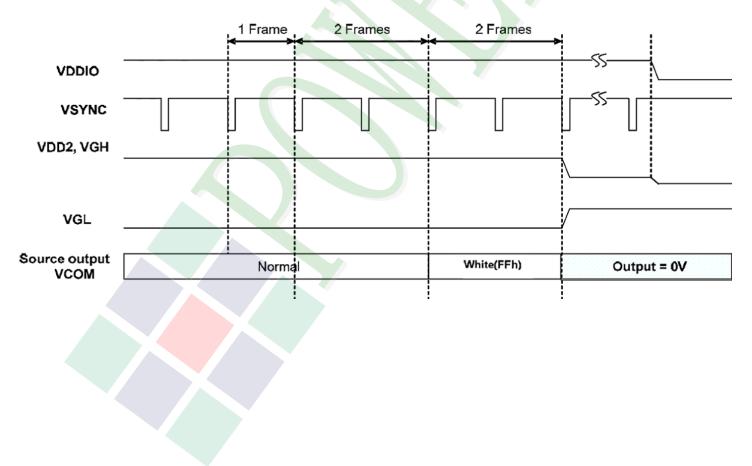


2.5 Power On/Off Sequence

2.5.1 Power On Sequence



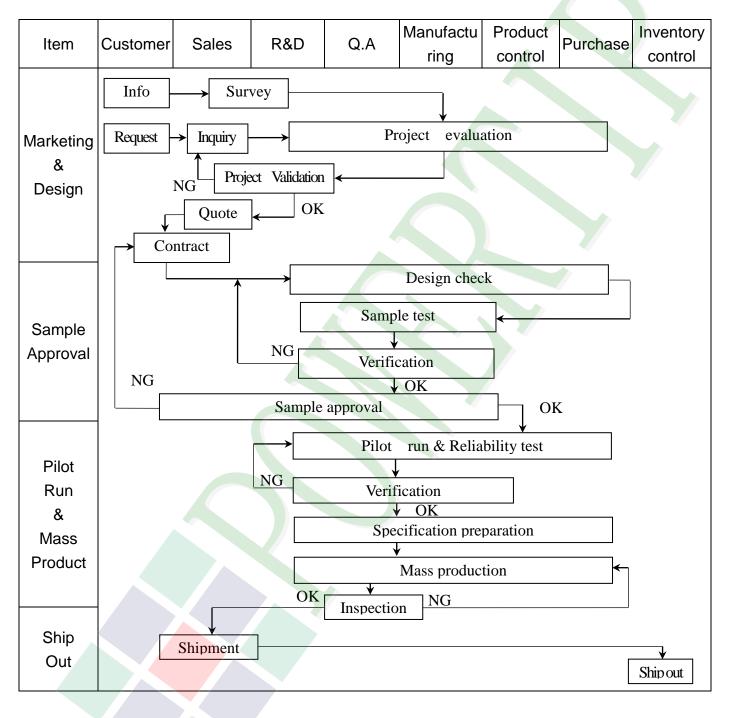
2.5.2 Power Off Sequence





3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart





ltem	Customer	Sales	R&D	Q.A	Manufact uring	Product control	Purchase	Inventory control
Sales Service	Info Analys	→ Claim sis report	[Trackin	Failure an Corrective			
Q.A Activity	1. ISO 9001 Maintenance Activities 3. Equipment calibration2. Process improvement proposal 4. Education And Training Activities5. Standardization Management				es			

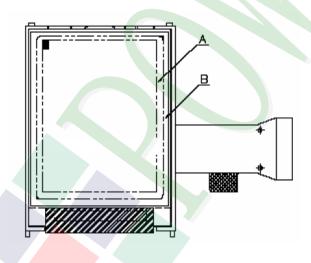
POWERTIP

3.2 Inspection Specification

- ◆Scope: The document shall be applied to TFT-LCD Module for 3. 5″ ~10″ (Ver.B01).
- ◆Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment : Gauge、MIL-STD、Powertip Tester、Sample
- ◆Defect Level : Major Defect AQL : 0.4 ; Minor Defect AQL : 1.5
- ♦OUT Going Defect Level : Sampling.
- ◆Standard of the product appearance test :
 - a. Manner of appearance test :
 - (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
 - (2). The test direction is base on about around 45° of vertical line.



(3). **Definition** of area.



A area : viewing area

B area : Outside of viewing area

(4). Standard of inspection : (Unit : mm)



◆Specification For TFT-LCD Module 3.5" ~ 10"

(Ver.B01)

NO	Item	Criterion	Level				
		1. 1The part number is inconsistent with work order of production.					
01	Product condition	1. 2 Mixed product types.					
		1. 3 Assembled in inverse direction.	Major				
02	Quantity	2. 1The quantity is inconsistent with work order of production.	Major				
03	Outline dimension	3.1 Product dimension and structure must conform to struct diagram.	ure Major				
		4. 1 Missing line character and icon.	Major				
		4. 2 No function or no display.	Major				
04	Electrical Testing	4. 3 Display malfunction.					
		4.4 LCD viewing angle defect.					
		4. 5 Current consumption exceeds product specifications.					
		Item Acceptance (Q'ty)					
		Sub pixelBright ≤ 2 ≤ 1 ≤ 0					
	Dot defect	$\begin{array}{ c c c c c c c c c c c c c c c c c c c$					
		Bright ≤ 1					
05	(Bright dot Dark dot)	Full pixel $Dark$ ≤ 1	Minor				
	On -display	 5. 1 One full pixel consists of 3 sub-pixels, including R,G and B dot (sub-pixel=Dot) 5. 2 Inspection pattern : full white , full black , Red , Green a blue screens. 5. 2 It is defined as dot defect if defect area >1/2 dot. 	•				



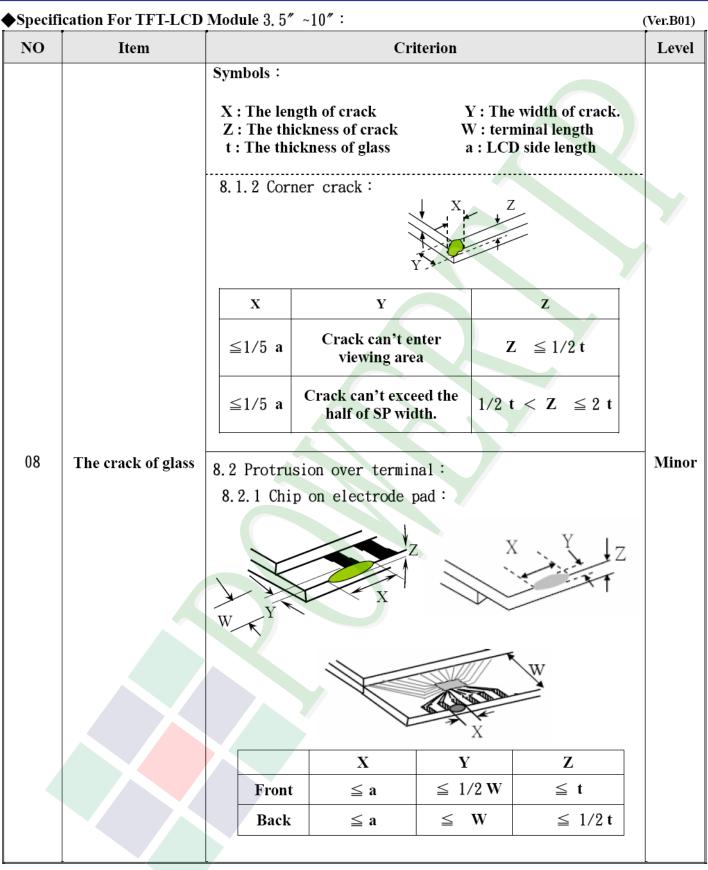
◆Specification For TFT-LCD Module 3. 5″~10″: (Ver							
NO	Item	Criterion					
		6. 1 Round type (Non-display or display) :					
		Dimension (diameter : Φ)Acceptance (Q'ty)A areaB area					
	Black or white dot、scratch、	$\Phi \leq 0.25$ Ignore					
	contamination	$0.25 < \Phi \leq 0.50 \qquad 5 \qquad \qquad \text{Ignore}$					
	Round type → _X ← ↓	$\Phi > 0.50$ 0					
	Y Y	Total 5					
06	$\Phi = (x+y)/2$	6. 2 Line type(Non-display or display) :	Minor				
	Line type	Length (L) Width (W) Acceptance (Q'ty)					
	Line type ↓	A area B area W ≤ 0.03 Ignore					
		L ≤ 10.0 0.03 W ≤ 0.05 Ignore					
		$L \leq 5.0 \qquad 0.05 < W \leq 0.10 \qquad 2 \qquad \text{Ignore}$					
		W >0.10 As round type					
		Total 5					
		Dimension (diameter : Φ)Acceptance (Q'ty)A areaB area					
		$\Phi \leq 0.25$ Ignore					
07	Polarizer	$0.25 < \Phi \leq 0.50$ 4	Minor				
	Bubble	$0.50 < \Phi \leq 0.80$ 1 Ignore					
		$\Phi > 0.80$ 0					
		Total 5					



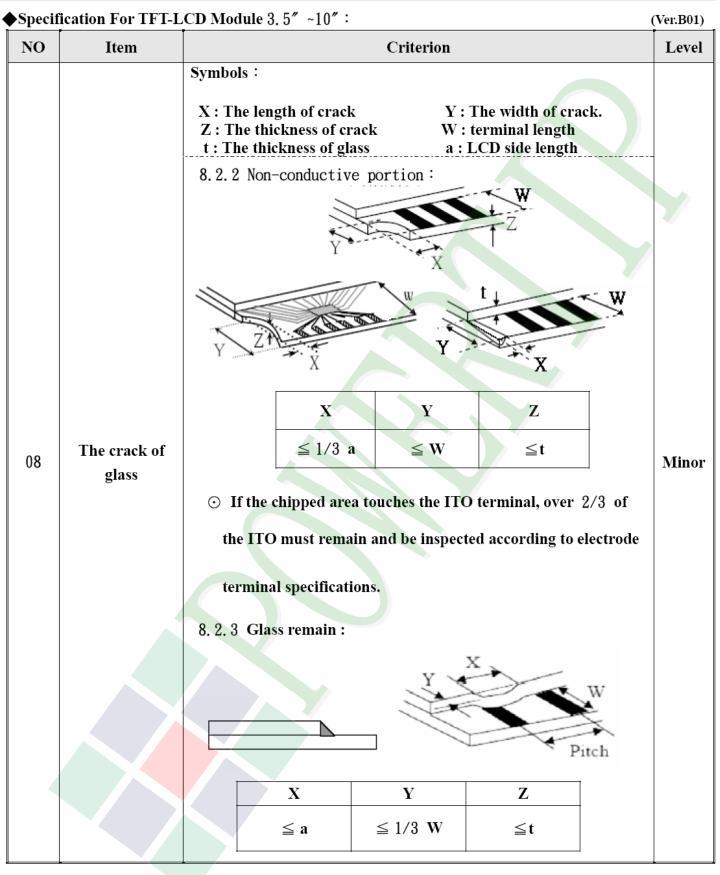
◆Specification For TFT-LCD Module 3. 5″~10″:

◆Specification For TFT-LCD Module 3. 5″~10″: (Ver.B						
NO	Item	Criterion		Level		
		Z : The thickness of crack V	Y : The width of crack. W : terminal length a : LCD side length			
		8.1 General glass chip: 8.1.1 Chip on panel surface and cra	nck between panels:	Y		
		Y Z Z	Z Y X Y			
08	The crack of glass	SP Y IOK]	ING]	Minor		
		Seal width	Y			
		XY	Z			
		≤ a Crack can't enter viewing area	$\leq 1/2 t$			
		$\leq a \qquad \begin{array}{c} Crack can't exceed the \\ half of SP width. \end{array}$	$1/2 t < Z \leq t$			











◆Specification For TFT-LCD Module 3. 5″~10″:

◆Specification For TFT-LCD Module 3. 5″~10″: (V						
NO	Item	Criterion	Level			
		9. 1 Backlight can't work normally.	Major			
09	Backlight elements		Major			
		9. 3 Illumination source flickers when lit.	Major			
		10. 1 Pin type < quantity < dimension must match type in structure diagram.	Major			
		10. 2 No short circuits in components on PCB or FPC .	Major			
	General	10.3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major			
10	appearance	10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor			
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor			
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≤1.5 mm.	Minor			



4. RELIABILITY TEST

4.1 Reliability Test Condition

(Ver. B01)

4.1	(ver. bul)						
NO.	TEST ITEM	TEST CO	NDITION				
1	High Temperature Storage Test	Keep in +80 ±2°C 240 hrs Surrounding temperature, then sto	rage at normal condition 4hrs.				
2	Low Temperature Storage Test	Keep in −30 ±2°C 240 hrs Surrounding temperature, then sto	Keep in $-30 \pm 2^{\circ}$ C 240 hrs Surrounding temperature, then storage at normal condition 4hrs.				
3	High Temperature / High Humidity Storage Test	Keep in +60 $^{\circ}$ C / 90% R.H duration for 240 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)					
4	Temperature Cycling Storage Test	(30mins) (5mins) ◀ 10 C	$-30^{\circ}\text{C} \rightarrow +25^{\circ}\text{C} \rightarrow +80^{\circ}\text{C} \rightarrow +25^{\circ}\text{C}$				
5	ESD Test	Discharge for each polarity +/-1. Temperature ambiance : 15°C ~2. Humidity relative : 30% ~60%3. Energy Storage Capacitance(Cs4. Discharge Resistance(Rd) : 3305. Discharge, mode of operation :	s+Cd):150pF±10% Ω±10% accessive discharges at least 1 sec)				
6	Vibration Test (Packaged)	 Sine wave 10~55 Hz frequency (1 min/sweep) The amplitude of vibration :1.5 mm Each direction (X \ Y \ Z) duration for 2 Hrs 					
7	Drop Test (Packaged)	Packing Weight (Kg) 0 ~ 45. 4 45. 4 ~ 90. 8 90. 8 ~ 454 Over 454 Drop Direction : %1 corner / 3 edge	122 76 61 46				
1							



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320\pm10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM .

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

